

ABSTRACT

The resist coating unit (COT) has a spin chuck (41) which holds the wafer to be supplied with a resist liquid, and a process cup (50) which accommodates the spin chuck (41) and exhausts an atmosphere around the wafer W from a bottom thereof. The process cup (50) comprises a first cup (51) with an outer circumferential wall (61a), and an airflow control member (52) laid out close to the wafer W in the first cup (51) in such a manner as to surround the wafer W. The airflow control member (52) has a vertical cross section of an approximately rectangular shape defined by the upper ring portion (62a) having a cross section of an approximately triangular shape and protruding upward, and a lower ring portion (62b) having a cross section of an approximately triangular shape and protruding downward. An exhaust passage (55) for substantially exhausting the atmosphere around the wafer W is formed between the outer circumferential wall (61a) and the airflow control member (52).